PC	N Number:	201907030	nn1	PCN Date:	Διια	15 2	019		
		TMP235, TMP23			Aug. 15, 2019				
Customer Contact:		PCN Manage			Dept:		Quality Services		
	ange Type:	<u>. c.t manag</u>	<u></u>			 -			
	Assembly Site			Design	ПП	Wafe	er Bump Site		
	Assembly Process			Data Sheet			r Bump Material		
				Part number change		Wafer Bump Process			
			Test Site		Wafer Fab Site				
	Packing/Shipping/Labeling T		Test Process		Wafer Fab Materials				
				uter - att - a Batatta	Wafer Fab Process				
Notification Details									
Description of Change: Texas Instruments Incorporated is announcing an information only notification.									
The product datasheet(s) is being updated as summarized below. The following change history provides further details.									
•	TEXAS INSTRUMENTS						TMP235, TMP236		
-				SE	30S857E	-SEPTEN	IBER 2017-REVISED MAY 2019		
Changes from Revision D (August 2018) to Revision E Page									
•	Changed recommended operating temperature range from: –50°C to 150°C to: –40°C to 150°C								
•	Changed power supply bypassing recommendations on how to avoid noise effect on the device output								
The datasheet number will be changing.									
Device Family			Change From:		Change To:				
TMP235, TMP236			SBOS857D		SBOS857E				
These changes may be reviewed at the datasheet links provided.									
http://www.ti.com/product/TMP235									
Re	ason for Change:								
То	accurately reflect d	evice charact	erist	ics.					
An	ticipated impact (on Fit, Form,	Fui	nction, Quality or Relia	bility	y (pos	sitive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes									
to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
_									
Pro	oduct Affected:								
	MP235A2DBZR	TMP235A	2DB	ZT TMP235A2D	CKR		TMP235A2DCKT		
TN		TMP235A							
NT NT	4P235A2DBZR	TMP235A TMP235A TMP236A	4DB	ZT TMP235A4D	CKR		TMP235A2DCKT TMP235A4DCKT TMP236A2DCKT		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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